Notice of References Cited Application/Control No. | Applicant(s)/Patent Under Reexamination HALL ET AL. | Examiner | Art Unit | José R. Díaz | 2815 | Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	Α	US-5,719,440	02-1998	Moden, Walter L.	257/697
	В	US-6,359,334 B1	03-2002	Jiang, Tongbi	257/706
	С	US-5,585,600 A	12-1996	Froebel et al.	174/52.4
	D	US-5,548,160 A	08-1996	Corbett et al.	257/666
	Е	US-5,840,598 A	11-1998	Grigg et al.	438/118
	F	US-			
	G	US-			
	Н	US-			
	1	US-			
	J	US-			
	К	US-			
	L	US-			
	М	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	0					
	Р					
	Q					
	R					
	S					
	Т					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)			
	U	Tummala et al., Microelectronics Packaging Handbook Semiconductor Packaging Part II, Chapman and Hall, 2 nd Ed., 1997, pages 25-26, 42-44, 91-93, 887-890.			
	v				
	w				
	х				

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).) Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.